

Title (en)

CONTACT MODULE FOR CONTACTING PRINTED CIRCUIT BOARDS

Title (de)

KONTAKTMODUL ZUR KONTAKTIERUNG VON LEITERPLATTEN

Title (fr)

MODULE DE CONTACT POUR LA MISE EN CONTACT DE CARTES DE CIRCUITS IMPRIMÉS

Publication

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Application

EP 21766675 A 20210830

Priority

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Abstract (en)

[origin: WO2022122198A1] The invention relates to a circuit board contact assembly (1) for making contact between a first printed circuit board (PCB1) and a second printed circuit board (PCB2), comprising at least two circuit board contacts (10) which have a connecting portion (11) at one contacting end thereof and a press-in zone (12) at the second contacting end thereof; at least one sealing member (20) which entirely surrounds the contacts in a central portion is provided between the connecting portion (11) and the press-in zone (12), the connecting portion (11) protruding from one lateral surface (21) of the sealing member (20) and the press-in zones (12) protruding from another lateral surface (22) of the sealing member (20).

IPC 8 full level

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